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Table of contents

Session T1B: Reliability

Probability of Failure due to Electrochemical Migration on Surface Mount Capacitor under Electrolyte Condition with same Contamination and Conductivity Level...1
Dr. Sajjad Bahrebar, Technical University of Denmark.

Session W1A: Application of novel packaging technologies

Encapsulation of biosensor for stress monitoring in fish: A study on design and material evaluation...10
Hanna Tomsdotter Bråthen, University of South-Eastern Norway

Stretchable Electronics for Large Area Sensor Skin...15
Christine Kallmayer, Fraunhofer IZM, Germany

Correlation between the characteristics of printed sinter paste and the quality of sintered interconnects through non-destructive analysis techniques...21
Fabien Steinberger, Technische Hochschule Ingolstadt, Germany

Session W1B: Materias for packaging solutions

Full-Aluminium-Powermodule...26
Christian Hennig, Kiel University of Applied Sciences, Germany

Low-temperature Cu-(Sn-Bi) Solid Liquid Interdiffusion Bonding – An initial study...32
Lisette Hernandez Gonzalez, University of South-Eastern Norway

Glass-LTCC-Interposer, a New Platform for HF-Applications (Best paper award)...36
Mahsa Kaltwasser, Technische Universität Ilmenau, Germany